Special Issue

Advances in Wireless Networks and Mobile Communication

Message from the Guest Editor

The rapid evolution of wireless networks and mobile communication technologies continues to revolutionize connectivity, enabling seamless data transmission, IoT integration, and next-generation applications. This Special Issue aims to explore cutting-edge advancements in 5G/6G networks. Al-driven optimization, edge computing, and ultra-reliable lowlatency communications. It also addresses emerging challenges in spectrum efficiency, security, and energyefficient protocols. By showcasing innovative research and practical solutions, this Issue aims to foster discussions on the future of mobile communication, empowering smarter, faster, and more resilient networks. We invite contributions that push the boundaries of wireless technology, driving progress toward a hyper-connected, intelligent digital ecosystem.

Guest Editor

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Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

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